



Product Change Notification: CAAN-10UJOE243

Date:

16-Jun-2026

Product Category:

Ethernet Bridges

Notification Subject:

CCB 8340 Final Notice: Qualification of MTAI as an additional assembly site for LAN7430/Y9X, LAN7430-I/Y9X, LAN7430T/Y9X and LAN7430T-I/Y9X catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package.

Affected CPNs:

[CAAN-10UJOE243_Affected_CPN_06162026.pdf](#)

[CAAN-10UJOE243_Affected_CPN_06162026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for LAN7430/Y9X, LAN7430-I/Y9X, LAN7430T/Y9X and LAN7430T-I/Y9X catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Microchip Technology Thailand (HQ)	Yes

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 16, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CAAN-10UJOE243_Pre and Post_Change_Summary.pdf

PCN_CAAN-10UJOE243_Qualification Report.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN):

LAN7430/Y9X

LAN7430-I/Y9X

LAN7430T/Y9X

LAN7430T-I/Y9X

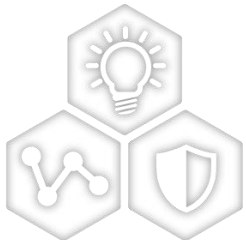
CCB 8340

Pre and Post Change Summary

PCN #: CAAN-10UJOE243

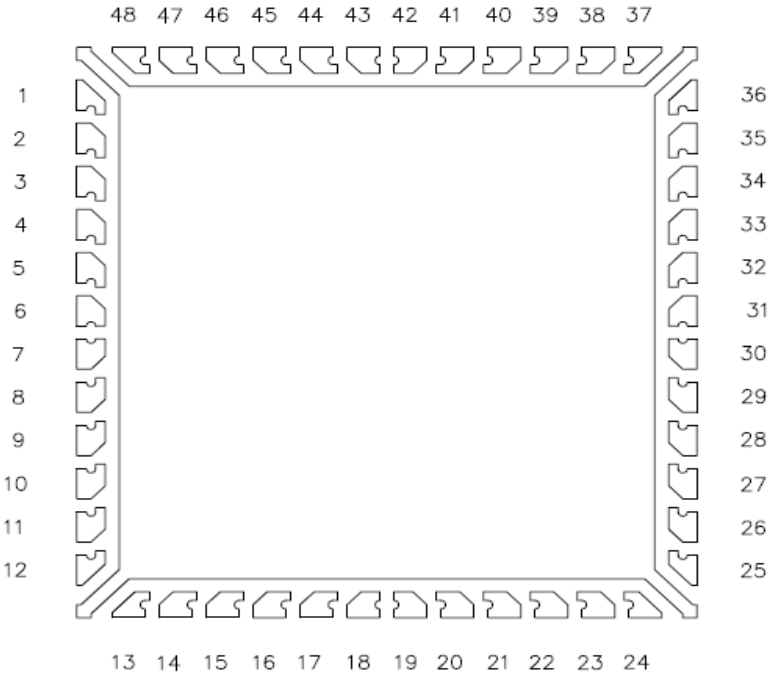
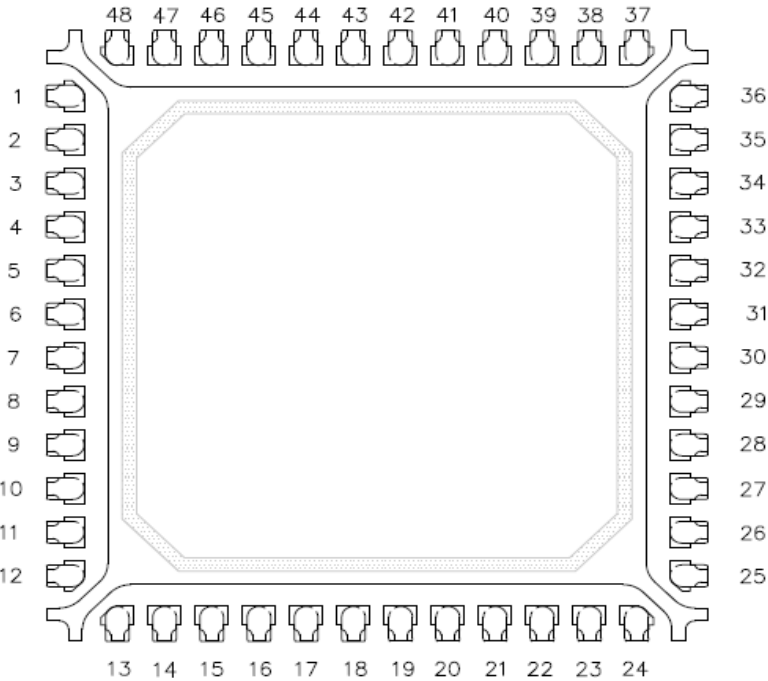


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LEAD FRAME COMPARISON

ASE		MTAI	
			
Lead frame Material	C194	Lead frame Material	C194

Note: Not to scale



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QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN#: CAAN-10UJOE243

Date:
June 16, 2026

Qualification of MTAI as an additional assembly site for LAN7430/Y9X, LAN7430-I/Y9X, LAN7430T/Y9X and LAN7430T-I/Y9X catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package. This is a Q006 grade 3 qualification and qualification by similarity (QBS).



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MTAI as an additional assembly site for LAN7430/Y9X, LAN7430-I/Y9X, LAN7430T/Y9X and LAN7430T-I/Y9X catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package. This is a Q006 grade 3 qualification and qualification by similarity (QBS).
CN	ES353881
QUAL ID	R2100291 Rev. A
MP CODE	STB037Y9XAB1
Part No.	LAN7800-I/Y9X
Bonding No.	BDM-002844 Rev. A
CCB No.	4572 (Qual Date: 05/20/21) and 8340
<u>Package</u>	
Type	48L VQFN
Package size	7 x 7 x 1.0 mm
<u>Lead Frame</u>	
Paddle size	224 x 224 mils
Material	C194
Surface	Ag ring plated on DAP
Process	Etched
Lead Lock	No
Part Number	10104817
<u>Material</u>	
Epoxy	3280
Wire	CuPdAu wire
Mold Compound	G700LTD
Plating Composition	Matte Sn



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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI215003167.000	TC14920515342.110	2111GM4
MTAI215003169.000	TC14920515342.110	2111GUQ
MTAI215003170.000	TC14920515342.110	2111GUR

Result

☒ Pass ☐ Fail ☐ _____

48L VQFN (7x7x1.0 mm) assembled by MTAI pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C
reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 3)	30°C/ 60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC C J-STD- 020E	135	0/135	Pass	
<u>Precondition Prior Perform Reliability Tests</u> (At MSL Level 3)	Electrical Test: +25°C and 85°C System: LTX_D1X Bake 150°C, 24 hrs System: CHINEE 30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 Electrical Test: +25°C and 85°C System: LTX_D1X	JESD22- A113	693(0)	693 693 693 0/693	 Pass	Good Devices

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +125°C, 1000 Cycles System: TABAI ESPEC TSA-70H Electrical Test: +85°C System: LTX_D1X	JESD22-A104		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45 (0)	0/45	Pass	
	Stress Condition: -55°C to +125°C, 2000 Cycles System: TABAI ESPEC TSA-70H Electrical Test: +85°C System: LTX_D1X		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 1.2 Volts, 2.5 Volts, 3.3 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 85°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45 (0)	0/45	Pass	
	Stress Condition: +130°C/85%RH, 192 hrs. Bias Volt: 1.2 Volts, 2.5 Volts, 3.3 Volts System: HAST 6000X			231		
	Electrical Test: +25°C and 85°C System: LTX_D1X		231(0)	0 /66	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 150°C, 500 hrs System: TPS DC-166-F-ST350	JESD22-A103		135		45 units / lot
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	
	Stress Condition: Bake 150°C, 1000 hrs System: TPS DC-166-F-ST350			135		
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	
Solderability Temp 215°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.215°C Solder material: SnPb Sn63, Pb37 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22 (0)	22 22 0/22	Pass	
Solderability Temp 245°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping:Solder Temp.245°C Solder material:Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22 (0)	22 22 0/22	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Physical Dimensions	Physical Dimension, 10 units / lot from 3 lot	JESD22- B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (>3.00 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>10.00 grams)	JESD22- B116	30 (0) bonds	0/30	Pass	



MICROCHIP

PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MTAI as an additional assembly site for LAN7430/Y9X, LAN7430-I/Y9X, LAN7430T/Y9X and LAN7430T-I/Y9X catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package. This is a Q006 grade 3 qualification and qualification by similarity (QBS).
CN	E000246496
QUAL ID	R2401317 Rev. A
MP CODE	STB071KDXC50
Part No.	USX5007C/KD
Bonding No.	BD-002245 Rev. 01
CCB No.	6910 (Qual Date: 03/04/25) and 8340
<u>Package</u>	
Type	100L VQFN
Package size	12 x 12 x 0.9mm
<u>Lead Frame</u>	
Paddle size	323 x 323mils
Material	EFTEC64
Surface	Ag signal ring plated on DAP
Process	Etched
Lead Lock	No
Part Number	10110011
Treatment	Roughening
<u>Material</u>	
Epoxy	QMI519
Wire	CuPdAu wire
Mold Compound	G700LTD
Plating Composition	Matte Sn



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI252600940.000	TC14924313854.200	2439YD7
MTAI252601144.000	TC14924313854.200	2439YT8
MTAI252601148.000	TC14924313854.200	2439YTK

Result

☒ Pass ☐ Fail ☐ _____

100L VQFN (12x12x0.9mm) assembled by MTAI pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C
reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 3)	30°C/ 60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC C J-STD- 020E	135(0)	0/135	Pass	
Precondition Prior Perform Reliability Tests (At MSL Level 3)	Electrical Test: +25°C and 85°C System: LTX_D1X Bake 150°C, 24 hrs System: CHINEE 30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 Electrical Test: +25°C and 85°C System: LTX_D1X	JESD22- A113	693(0)	0/693 693 693 693 0/693	Pass Pass	Good Devices

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +125°C, 500 Cycles System : VOTSCH Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	JESD22-A104		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	
			45 (0)	0/45	Pass	
	Stress Condition: -55°C to +125°C, 1000 Cycles System: VOTSCH Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)			231		
			231(0)	0/231	Pass	
			45 (0)	0/45		

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: +110°C/85%RH, 264 hrs. Bias Volt: PS1:1.32 Volts, PS3: 3.63 Volts System: HAST 6000X Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	JESD22-A110		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	77 units / lot
			45 (0)	0/45	Pass	
	Stress Condition: +110°C/85%RH, 528 hrs. Bias Volt: PS1:1.32 Volts, PS3:3.63 Volts System: HAST 6000X Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	JESD22-A110		231		
			231(0)	0/231	Pass	
			45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	Stress Condition: +110°C/85%RH, 264 hrs. System: HAST 6000X	JESD22- A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 150°C, 500 hrs System: CHINEE	JESD22- A103		135		45 units / lot
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	
	Stress Condition: Bake 150°C, 1000 hrs System: CHINEE			135		
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Cross section	Cross section Inspection 5 units / lot		15(0) Wires	0/15	Pass	
Bond Strength	Wire Pull (> 3.00 grams)	Mil. Std. 883-2011	30 (0) Wires	0/30	Pass	
Data Assembly	Bond Shear (>8.00 grams)	CDF-AEC- Q100-001	30 (0) Bonds	0/30	Pass	